

ABSTRACT

MOLDED CIRCUIT SUBSTRATES

Molded circuit substrates include a conductive layer surrounded by an insulating sidewall. The insulating sidewall further provides a structural component for an electronic module into which the molded circuit substrate is incorporated. Accordingly, the molded circuit substrates can permit better performance, reduce electronic module thickness, and reduce fabrication costs. Methods for fabricating molded circuit substrates can facilitate precise positioning of insulating sidewalls, insulating partitions, electrical contacts and other components.

Fig. 2B